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- Combines Decoder and 3-Bit Address Latch
- Incorporates Two Output Enables to Simplify Cascading
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

SN54ALS137A, SN74ALS137A, The and SN74AS137 are 3-line to 8-line decoders/ demultiplexers with latches on the three address inputs. When the latch-enable (\overline{LE}) input is low, the devices act as decoders/demultiplexers. When LE goes from low to high, the address present at the select (A. B. and C) inputs is stored in the latches. Further address changes are ignored as long as LE remains high. The output-enable controls (G1 and $\overline{G2}$) control the outputs independently of the select or latch-enable inputs. All of the outputs are forced high if G1 is low or $\overline{G2}$ is high. These devices are ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

The SN54ALS137A is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS137A and SN74AS137 are characterized for operation from 0°C to 70°C.

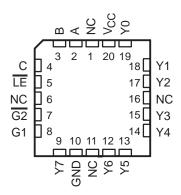
	•			
A [B [C [G2 [G1 [Y7 [GND [3	U	16 15 14 13 12 11 10 9	V _{CC} Y0 Y1 Y2 Y3 Y4 Y5 Y6

SN54ALS137A ... J PACKAGE

SN74ALS137A, SN74AS137 ... D OR N PACKAGE

(TOP VIEW)

SN54ALS137A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

	FUNCTION TABLE												
		INP	JTS						OUT	PUTS			
	ENABLE			SELECT	•								
LE	G1	G2	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Х	Н	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	L	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
L	Н	L	L	Н	L	н	Н	L	Н	Н	Н	Н	н
L	Н	L	L	Н	Н	н	Н	Н	L	Н	Н	Н	н
L	Н	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
L	Н	L	н	L	Н	н	Н	Н	Н	Н	L	Н	н
L	Н	L	Н	Н	L	н	Н	Н	Н	Н	Н	L	Н
L	Н	L	н	Н	Н	н	Н	Н	Н	Н	Н	Н	L
Н	Н	L	Х	Х	Х	Out	outs corr	espondir	ng to stor	ed addre	ess = L; a	all others	= H

FUNCTION TABLE

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

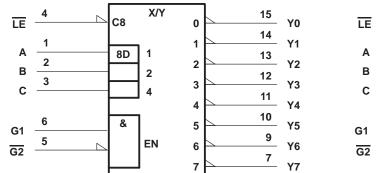
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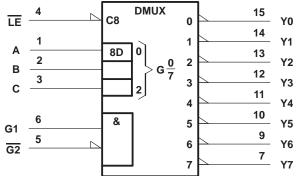
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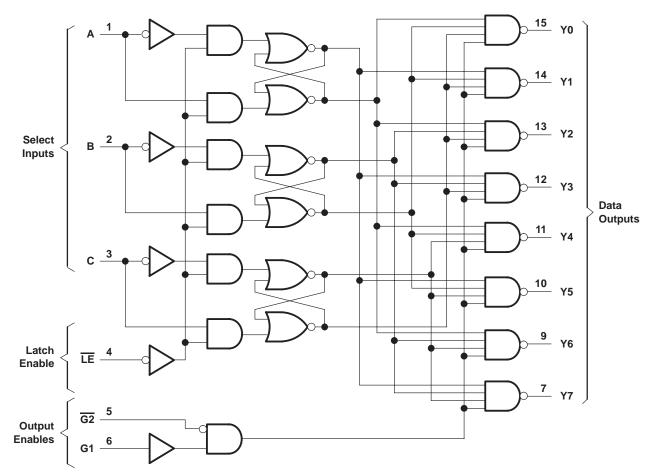
logic symbols (alternatives)[†]





 † These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I	
Operating free-air temperature range, T _A : SN54ALS137A	−55°C to 125°C
SN74ALS137A	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS137A		57A	SN7	4ALS13	7A	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
tw	Pulse duration, LE low	15			10			ns
t _{su}	Setup time at A, B, and C before \overline{LE}^{\uparrow}	15			10			ns
t _h	Hold time at A, B, and C after \overline{LE}^{\uparrow}	5			5			ns
Тд	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS			57A	SN7			
PARAMETER	TEST C	TEST CONDITIONS				MIN	typ‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = – 18 mA			-1.5			-1.5	V
VOH	V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2	2		V
	V _{CC} = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V _{OL}		$I_{OL} = 8 \text{ mA}$					0.35	0.5	v
Ц	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
۱ _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V			5	11		5	11	mA

[‡] All typical values are at V_{CC} = 5 V, $T_A = 25^{\circ}C$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L RI	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [†]					
	((,	SN54AL	.S137A	SN74ALS137A				
			MIN	MAX	MIN	MAX			
^t PLH		Y	5	25	5	20	ns		
^t PHL	A, B, C		6	25	6	20			
^t PLH	G2	v	4	15	3	12	ns		
^t PHL	G2	Y	5	18	4	15			
^t PLH		× ×	5	21	4	17			
^t PHL	G1	Y	5	19	4	15	ns		
^t PLH		Y	7	27	6	22			
^t PHL		I I	7	25	7	20	ns		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	7V
Input voltage, V _I	7V
Operating free-air temperature range, T _A : SN74AS137 0°C t	o 70°C
Storage temperature range	150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN74AS137		
		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-2	mA
IOL	Low-level output current			20	mA
tw	Pulse duration, LE low	6.5			ns
t _{su}	Setup time at A, B, and C before \overline{LE}^{\uparrow}	4			ns
t _h	Hold time at A, B, and C after LE↑	1			ns
Т _А	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN	SN74AS137				
PARAMETER	TEST COND	MIN	түр†	MAX	UNIT		
VIK	$V_{CC} = 4.5 V,$	lı = – 18 mA			-1.2	V	
VOH	V_{CC} = 4.5 V to 5.5 V,	I _{OH} = -2 mA	V _{CC} -2			V	
V _{OL}	$V_{CC} = 4.5 V,$	I _{OL} = 20 mA		0.35	0.5	V	
l	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1	mA	
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA	
۱ _{۱L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-1	mA	
I0 [‡]	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		- 112	mA	
lcc	V _{CC} = 5.5 V			15	24	mA	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

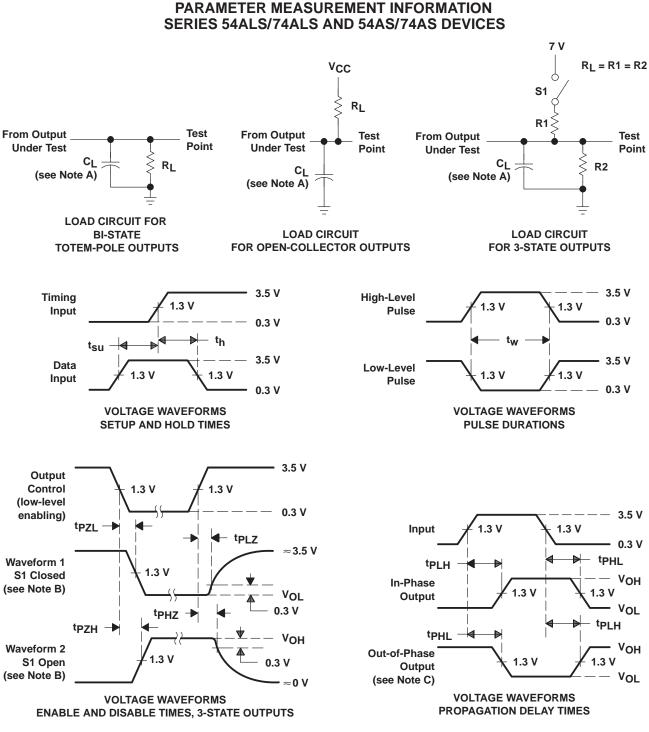
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L = 50 pF R _L = 500 Ω T _A = MIN t	$V_{CC} = 4.5 V \text{ to } 5.5 V, \\ C_{L} = 50 \text{ pF}, \\ R_{L} = 500 \Omega, \\ T_{A} = \text{MIN to MAX} \\ \hline \text{SN74AS137}$			
			MIN	MAX	1		
^t PLH		, v	2	12.5	ns		
^t PHL	А, В, С	Y	2	12.5			
^t PLH	G2	Y	2	8	ns		
^t PHL	G2	Ý	2	8.5			
^t PLH	04	, v	2	10			
^t PHL	G1	Y	2	9	ns		
^t PLH	LE	Y	3	13.5	ns		
^t PHL		Ť	3	14			

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS137AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS137A	Samples
SN74ALS137AN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS137AN	Samples
SN74ALS137ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS137AN	Samples
SN74AS137D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74AS137DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74AS137N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI	0 to 70		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

17-Dec-2015

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS137A, SN74ALS137A :

- Catalog: SN74ALS137A
- Military: SN54ALS137A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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